

ABSTRACT

The present invention relates to thermosetting resin compositions which are suitably used for manufacturing circuit boards, such as flexible printed circuit boards (FPCs) and build-up circuit boards, and to multilayer bodies and circuit boards manufactured using such thermosetting resin compositions.

A thermosetting resin composition contains a polyimide resin component (A), a phenol resin component (B), and an epoxy resin component (C). The mixing ratio by weight (A)/[(B)+(C)] is in a range of 0.4 to 2.0, the mixing ratio by weight being the ratio of the weight of the component (A) to the total weight of the component (B) and the component (C). By using such a thermosetting resin composition, it is possible to manufacture multilayer bodies and circuit boards which are excellent in dielectric characteristics, adhesiveness, processability, heat resistance, flowability, etc.

A thermosetting resin composition contains a polyimide resin (A), a phosphazene compound (D), and a cyanate ester compound (E). The phosphazene compound (D) includes a phenolic hydroxyl group-containing phenoxyphosphazene compound (D-1) and/or a crosslinked phenoxyphosphazene compound (D-2) prepared by crosslinking the phenoxyphosphazene compound (D-1), the crosslinked

phenoxyphosphazene compound (D-2) having at least one phenolic hydroxyl group. By using such a thermosetting resin composition, it is possible to manufacture multilayer bodies and circuit boards which are excellent in dielectric
5 characteristics, processability, heat resistance, and flame retardance.